

GM2305A**P-CHANNEL ENHANCEMENT MODE POWER MOSFET**

BVDSS	-30V
RDS(ON)	80mΩ
ID	-3.2A

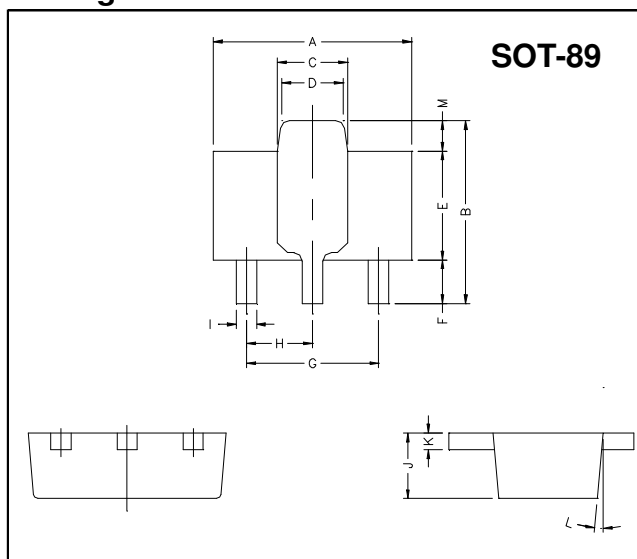
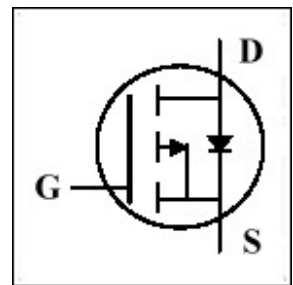
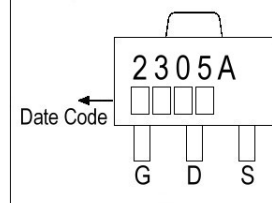
Description

The GM2305A provide the designer with best combination of fast switching, low on-resistance and cost-effectiveness.

The GM2305A is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

Features

- *Simple Drive Requirement
- *Surface Mount Device

Package Dimensions**Marking :**

REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.4	4.6	G	3.00	REF.
B	4.05	4.25	H	1.50	REF.
C	1.50	1.70	I	0.40	0.52
D	1.30	1.50	J	1.40	1.60
E	2.40	2.60	K	0.35	0.41
F	0.89	1.20	L	5° TYP.	
			M	0.70 REF.	

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ³	$I_D @ T_A = 25^\circ C$	-3.2	A
Continuous Drain Current ³	$I_D @ T_A = 70^\circ C$	-2.6	A
Pulsed Drain Current ^{1,2}	I_{DM}	-10	A
Power Dissipation	$P_D @ T_A = 25^\circ C$	1.5	W
Linear Derating Factor		0.012	W/ $^\circ C$
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 ~ +150	$^\circ C$

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-ambient ³ Max.	R_{thj-a}	83.3	$^\circ C/W$

Electrical Characteristics (T_j = 25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV _{DSS}	-30	-	-	V	V _{GS} =0, I _D =-250uA
Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} / ΔT _j	-	-0.1	-	V/°C	Reference to 25°C, I _D =-1mA
Gate Threshold Voltage	V _{GS(th)}	-0.5	-	-1.2	V	V _{DS} =V _{GS} , I _D =-250uA
Forward Transconductance	g _{fs}	-	9	-	S	V _{DS} =-5V, I _D =-3A
Gate-Source Leakage Current	I _{GSS}	-	-	±100	nA	V _{GS} = ±12V
Drain-Source Leakage Current(T _j =25°C)	I _{DSS}	-	-	-1	uA	V _{DS} =-30V, V _{GS} =0
Drain-Source Leakage Current(T _j =70°C)		-	-	-25	uA	V _{DS} =-24V, V _{GS} =0
Static Drain-Source On-Resistance	R _{DS(ON)}	-	-	65	mΩ	V _{GS} =-10V, I _D =-3.2A
		-	-	80		V _{GS} =-4.5V, I _D =-3.0A
		-	-	150		V _{GS} =-2.5V, I _D =-2.0A
		-	-	250		V _{GS} =-1.8V, I _D =-1.0A
Total Gate Charge ²	Q _g	-	10	18	nC	I _D =-3.2A
Gate-Source Charge	Q _{gs}	-	1.8	-		V _{DS} =-24V
Gate-Drain ("Miller") Charge	Q _{gd}	-	3.6	-		V _{GS} =-4.5V
Turn-on Delay Time ²	T _{d(on)}	-	7	-	ns	V _{DS} =-15V
Rise Time	T _r	-	15	-		I _D =-3.2A
Turn-off Delay Time	T _{d(off)}	-	21	-		V _{GS} =-10V
Fall Time	T _f	-	15	-		R _G =3.3Ω R _D =4.6Ω
Input Capacitance	C _{iss}	-	735	1325	pF	V _{GS} =0V
Output Capacitance	C _{oss}	-	100	-		V _{DS} =-25V
Reverse Transfer Capacitance	C _{rss}	-	80	-		f=1.0MHz

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V _{SD}	-	-	-1.2	V	I _S =-1.2A, V _{GS} =0V
Reverse Recovery Time ²	T _{rr}	-	24	-	ns	I _S =-3.2A, V _{GS} =0V dI/dt=100A/μs
Reverse Recovery Charge	Q _{rr}	-	19	-	nC	

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width ≤ 300us, duty cycle ≤ 2%.

3. Surface mounted on FR4 board, t ≤ 10sec.

Characteristics Curve

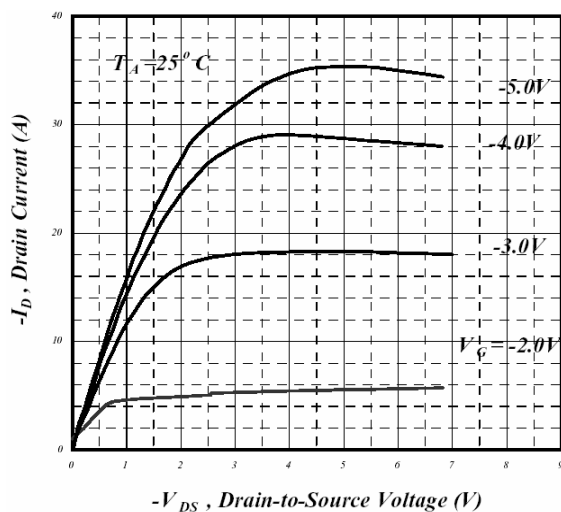


Fig 1. Typical Output Characteristics

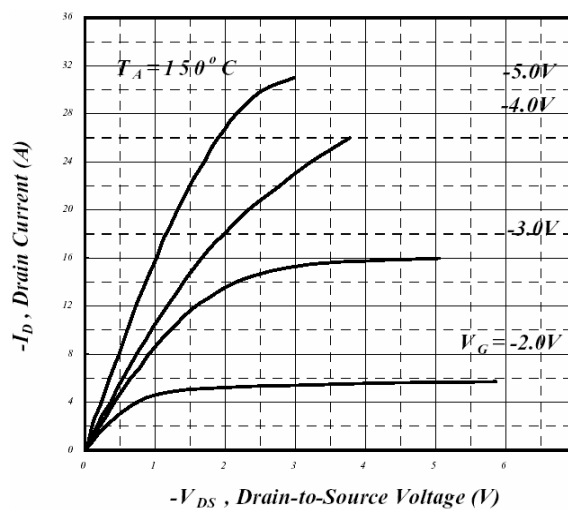


Fig 2. Typical Output Characteristics

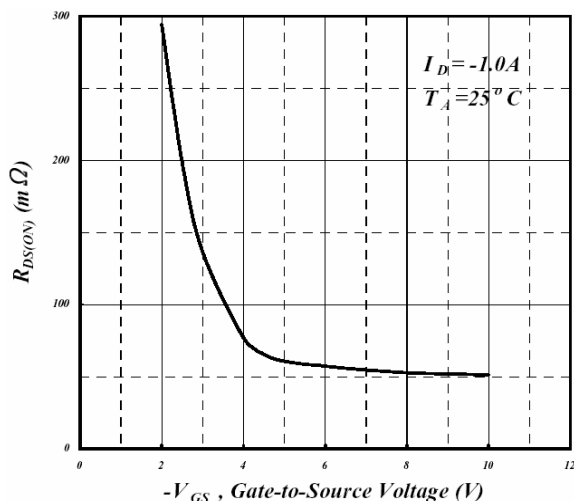


Fig 3. On-Resistance v.s. Gate Voltage

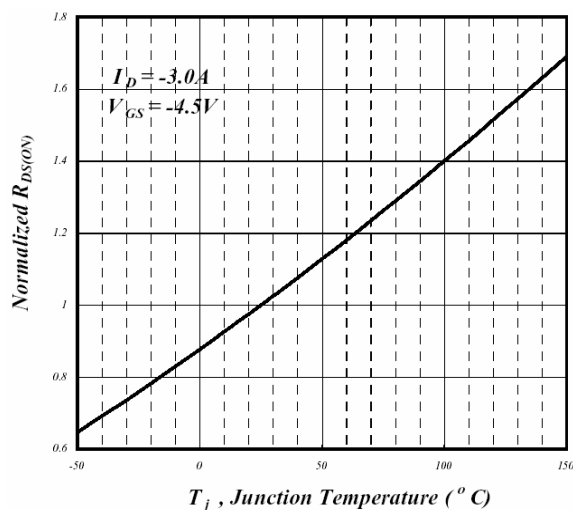


Fig 4. Normalized On-Resistance v.s. Junction Temperature

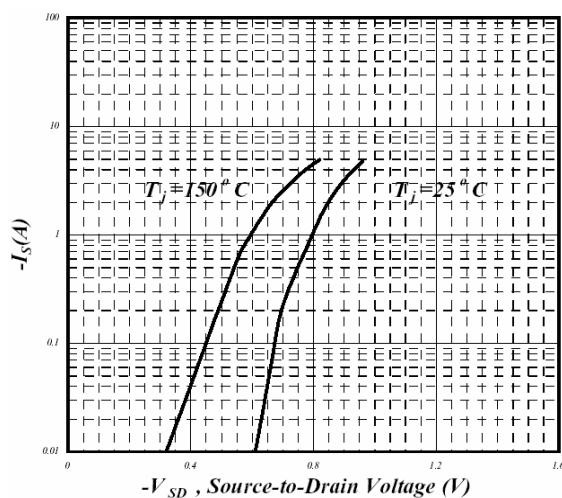


Fig 5. Forward Characteristics of Reverse Diode

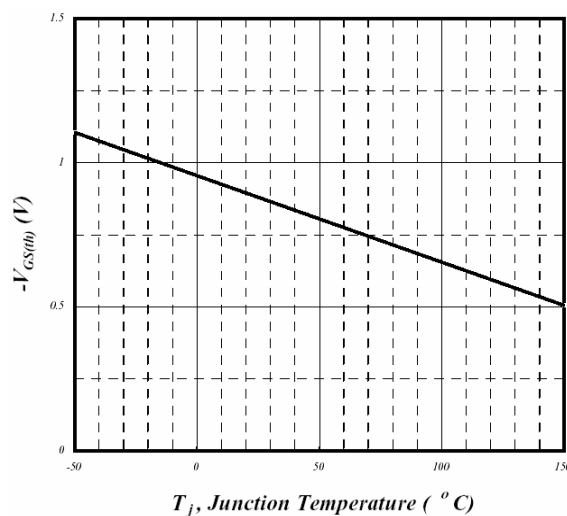
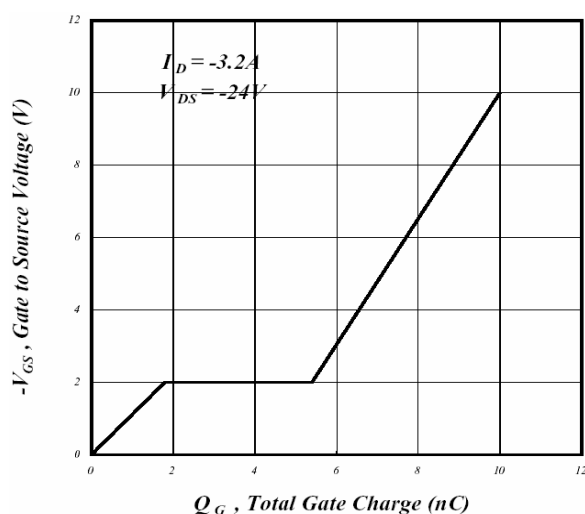
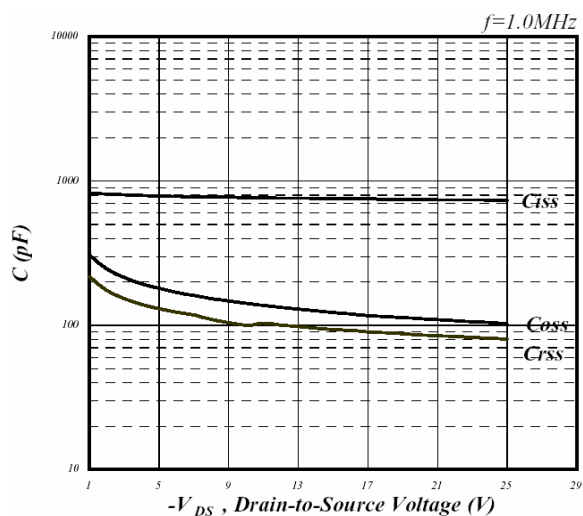
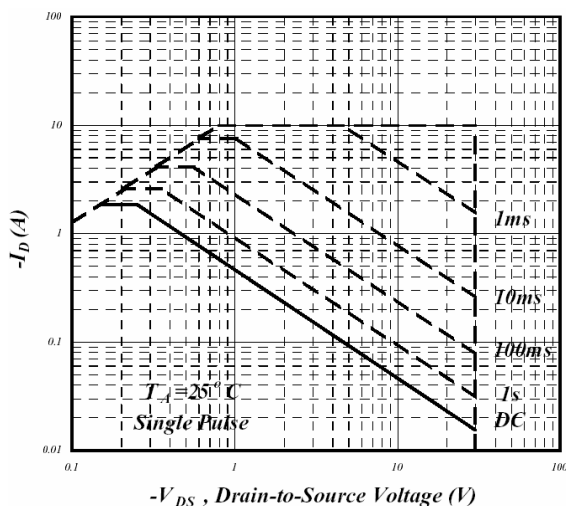
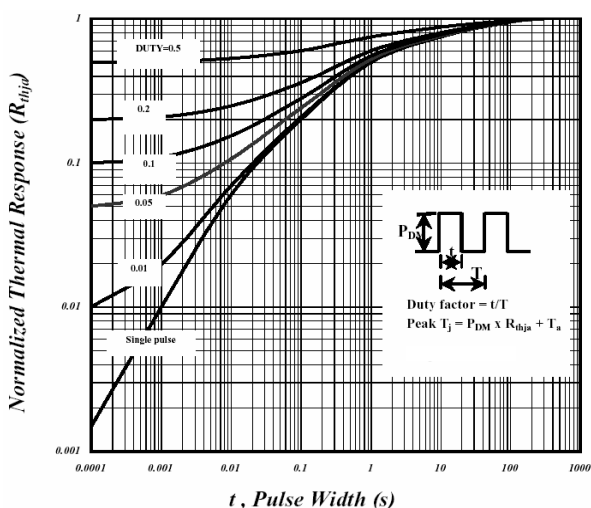
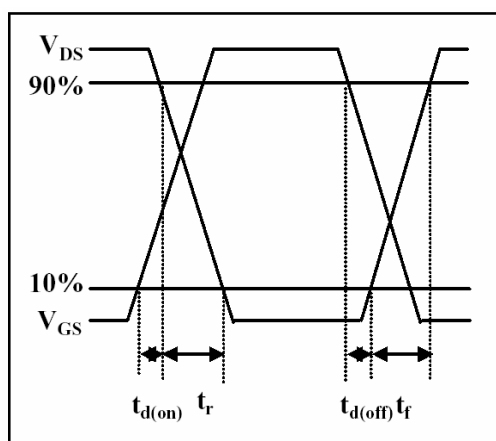
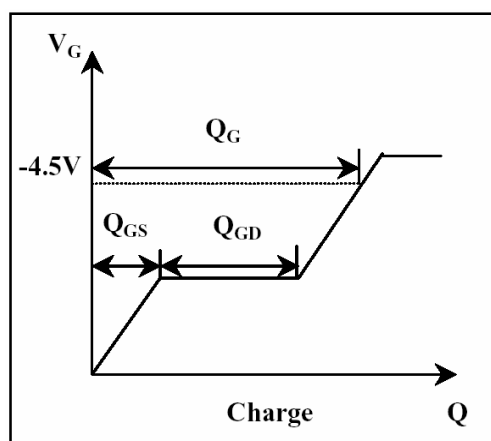


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

**Fig 7. Gate Charge Characteristics****Fig 8. Typical Capacitance Characteristics****Fig 9. Maximum Safe Operating Area****Fig 10. Effective Transient Thermal Impedance****Fig 11. Switching Time Waveform****Fig 12. Gate Charge Waveform****Important Notice:**

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